

## CLAIMS

1. A conductive particle of which the surface of a base particle is covered with a conductive film or conductive films and which has projections formed by projecting of said conductive film or conductive films, wherein a core material for projecting the surface of said conductive film is provided on the surface of said base particle and said core material is composed of a conductive material different from a conductive material composing said conductive film or conductive films.

2. The conductive particle according to claim 1, wherein said core material has a shape in lump form.

3. The conductive particle according to claim 1 or 2, wherein the outermost surface of said conductive film is a gold layer.

4. A conductive particle, wherein said conductive particle has a core material in particle form, composed of a conductive material, on the surface of a base particle, said base particle and said core material are covered with a plated coat and said conductive particle has projections formed by projecting of the surface of said plated coat by thus covering said core material.

5. The conductive particle according to claim 4, wherein at least 80% or more of said core material existing on the surface of said base particle contacts with said base particle or exists within a range of 5 nm from said base particle.

6. The conductive particle according to claim 4 or 5, wherein the outermost surface of said plated coat is a gold layer.

7. The conductive particle according to any one of claims 1 to 6, wherein said core material is composed of at least one or more species of metal.

8. The conductive particle according to any one of claims 1 to 7, wherein said base particle is a resin particle.

9. The conductive particle according to any one of claims 1 to 8, wherein an average height of said projection portions projecting is 0.5% or more of an average particle diameter of the conductive particles.

10. An anisotropic conductive material, wherein the conductive particles according to any one of claims 1 to 9 are dispersed in a resin binder.